

PRODUCT BRIEF | MCP

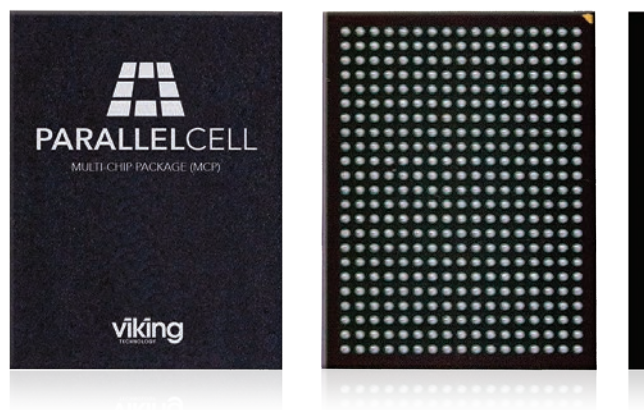
MULTI-CHIP PACKAGE (MCP)

Military Grade Ultra High Density Memory Solution for Embedded Applications

Viking Technology's Multi-Chip Package (MCP) is part of the extreme density line of DDR4 memory products optimized for the embedded, industrial, and military/aerospace markets.

DDR4 MCP products achieve significantly higher memory performance and density per cubic inch than conventional memory DIMMs. These performance and density milestones will critically change the way future system hardware is designed and deployed.

DDR4 densities available in 4GB, 8GB, and now 16GB (x72)



BENEFITS

Very small footprint: Saves up to 85% board space vs. Standard DIMM Modules

Very high memory capacity per cu. in.

Very high memory bandwidth per cu. in.

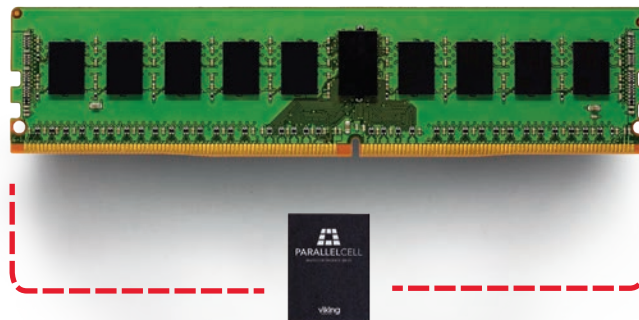
Rugged: Soldered-down – No DIMM connector

Superior signal integrity

Lower cost motherboard due to easier DDR routing

SPEEDS		VOLTAGE
DDR4	2133/2400/2667/2933	1.2V
TEMPERATURE		
Commercial	0°C to +70°C	
Industrial	-40°C to +85°C	
Automotive	-40°C to +105°C	
Military	-55°C to +125°C	
CAPACITY		
4GB/8GB/16GB/*32GB		

* 32GB Capacity planned for future development



Available in: 15mm x 20mm and 13mm x 20mm

Made in the USA 

MULTI-CHIP PACKAGE (MCP)

Military Grade Ultra High Density Memory Solution for Embedded Applications

THE VIKING VALUE ADVANTAGE

- ▶ ITAR & AS9100, TL 9000 & ISO 14001 Certified
- ▶ USA based R&D, Development & Production
- ▶ Advanced Packaging Expertise
- ▶ DoD specified testing capabilities (i.e. TDBI)
- ▶ Long-standing strategic partnerships & comprehensive supply-chain management
- ▶ Obsolescence mitigation
- ▶ Locked BOM under customer PCN control
- ▶ Localized Field Application Engineering for complete pre & post sale technical support



MILITARY APPLICATIONS

Viking Technology's DDR4 Multi-Chip Package products are designed for the rugged environment of military and space applications. They are rigorously tested and independently verified to MIL-STD-883 to operate in harsh environments:

- ▶ SWaP-optimized
- ▶ Space-constrained
- ▶ Vehicle-based
- ▶ High Shock & Vibration
- ▶ Ruggedized
- ▶ Harsh Environments
- ▶ Extended Temp

REAL-WORLD APPLICATION DEPLOYMENTS

- ▶ Military Satellite
- ▶ Fighter Jets
- ▶ Unmanned Aerial Vehicles (UAV)
- ▶ Autonomous Vehicles
- ▶ Communication Satellites (LEO and Rad Tolerant)
- ▶ Communication Radio
- ▶ Embedded Satellite
- ▶ Avionics Video Capturing

For price and availability, please email us at sales@vikingtechnology.com.



Global Locations

US Headquarters

2950 Red Hill Avenue
Costa Mesa, CA 92626
Main: +1 714 913 2200
Fax: +1 714 913 2202

India Engineering Office

A 3, Phase II, MEPZ-Special Economic Zone
NH 45, Tambaram, Chennai-600045
India

Singapore Office

No 2 Chai Chee Drive
Singapore, 109840

For all of our global locations, visit our website under global locations. For sales information, email us at sales@vikingtechnology.com